National Semiconductor
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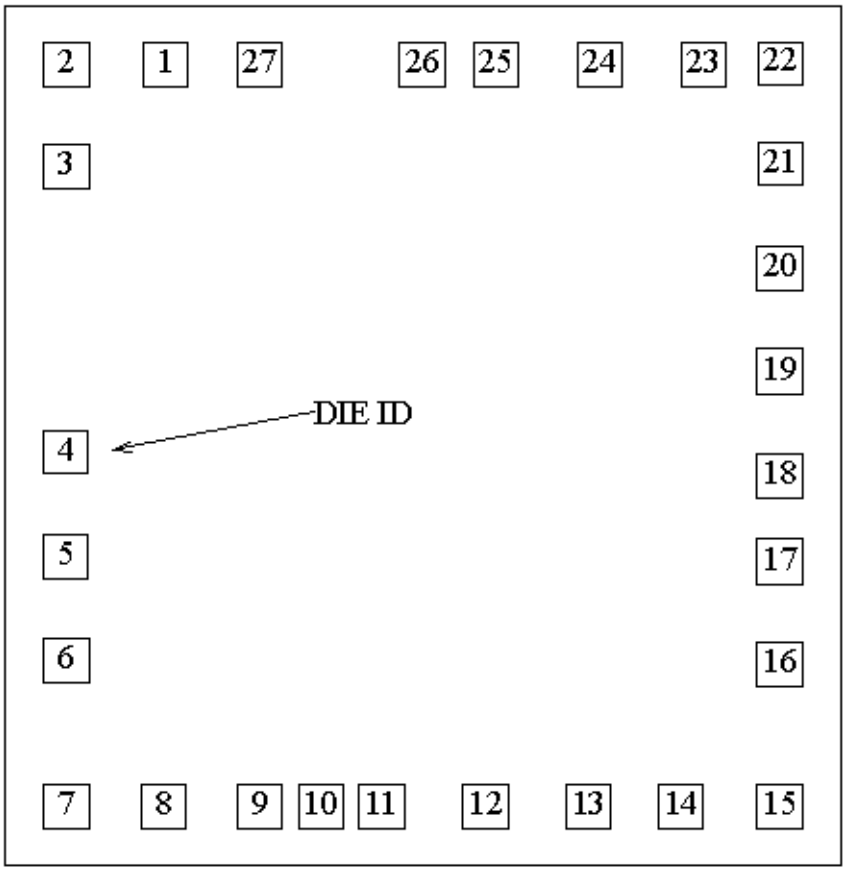
DPBU
Die Datasheet

DP83211 MWF MCD1200A

March 05,2004

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DP83211A	Bond Pad Opening Size (min)	94µm x 94µm
Die Step	A	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	PIQ OVER NITRIDE OVER VAPOX
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1828µm x 1879µm 72.0mils x 74.0mils	Back Side Connection	GND
Thickness	406µm Nominal		
Min Pitch	169µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
Pad	1	-562	811	98	x	98
Pad	2	-779	811	98	x	98
Pad	3	-779	587	98	x	98
Pad	4	-781	-37	94	x	94
Pad	5	-781	-264	94	x	94
Pad	6	-779	-491	98	x	98
Pad	7	-779	-811	98	x	98
Pad	8	-566	-811	98	x	98
Pad	9	-358	-811	98	x	98
Pad	10	-224	-811	98	x	98
Pad	11	-91	-811	98	x	98
Pad	12	136	-811	98	x	98
Pad	13	362	-811	98	x	98
Pad	14	564	-811	98	x	98
Pad	15	779	-811	98	x	98
Pad	16	779	-501	98	x	98
Pad	17	779	-275	98	x	98
Pad	18	779	-87	98	x	98
Pad	19	779	140	98	x	98
Pad	20	779	366	98	x	98
Pad	21	781	593	94	x	94
Pad	22	781	813	94	x	94
Pad	23	612	811	98	x	98
Pad	24	386	811	98	x	98
Pad	25	159	811	98	x	98
Pad	26	-2	811	98	x	98
Pad	27	-358	811	98	x	98

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